

**OMNIMATE Housing – serie CH20M6
LHZ-SMT R 1.5SN BK RL****Weidmüller Interface GmbH & Co. KG**

Klingenbergstraße 16

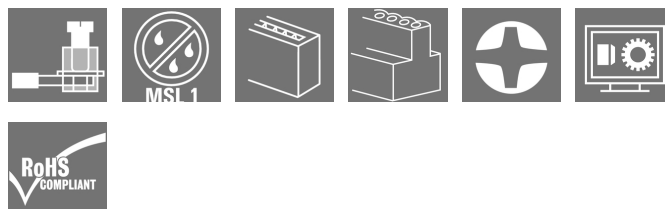
D-32758 Detmold

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**Elektronikvärlden i en plint.**

Med en bredd på endast 6,1 mm kan elektronikutvecklaren med sitt Know-How skapa kompakta applikationsvärldar.

Det modulära kapslingskonceptet stöder konstruktionen med en rad intelligenta egenskaper:

- **Maximal designfrihet** genom stor netto-yta (6800 mm²) på kretskortet för maximal bestyckning genom platssparande geometri hos de reflow- och THR-anpassade stiftlisterna.
- **Individuella designmöjligheter** genom märknings- och färgalternativ för kapslingarna, samt variabelt och enkelt märkbart öppningsbart lock som kan bearbetas individuellt
- **Maximal effektivitet** i hanteringen genom reflow-kompatibla, automatanpassade anslutningselement för reflow-lödning förpackade i band.
- **Felfria bestycknings- och lödprocesser** genom optimerad ramgeometri för kretskortsutnyttjandet och stödgeometri för ett exakt läge hos anslutningselementen.
- **Tidssparande installation** tack vare egenskaper som "Wire Ready", eller den universella plus-minus-skruven

Elektronikutvecklarens Know-How och Weidmüllers kompetens - ett innovativt och framgångsrikt team vid skapandet av elektronikapplikationer.

Allmänna beställningsdata

Typ	LHZ-SMT R 1.5SN BK RL
Art.nr.	2418590000
Artikelbeteckning	Kretskortsplint, Anslutningselement höger, Blockbyggsätt, stängd på sidan, THT/THR lödanslutning, Antal poler: 1, Lödstiftlängd (l): 1.5 mm, förtennad, svart, Tape
GTIN (EAN)	4032248984343
Frp	432 Stück
Produktparametrar	IEC: 500 V / 0.2 - 2.5 mm ² UL:
Förpackning	Tape

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Tekniska data**Mått och vikter**

Längd	23,5 mm	Bygglängd (tum)	0,925 inch
Bredd	6 mm	Byggbredd (tum)	0,236 inch
Höjd	16,9 mm	Bygghöjd (tum)	0,665 inch
Nettovikt	3,34 g		

Karakteristiska systemvärden

Utförande	Anslutningselement höger	Anslutningstyp	Klämbygelanslutning
Antal anslutningar	1	Kretskortstjocklek	0,8 mm
Lödstiftlängd (l)	1,5 mm	Typ av kretskortskontaktering	Reflow
Kontakt till montageskena	Nej	Skyddsklass	IP20

Materialdata

Isoleringsmaterial	LCP	Färgkod	svart
Färgtabell (jämförbar)	RAL 9011	Isoleringsmaterialgrupp	IIla
CTI	≥ 175	Isolationshållfasthet	≥ 10 ⁸ Ω
Moisture Level (MSL)	1	Brännbarhetsklass enligt UL 94	V-0
Kontakttyta	förtennad	Lagertemperatur, min.	-25 °C
Lagertemperatur, max.	55 °C	relativ fuktighet vid lagring, max	80 %
Driftstemperatur, min.	-40 °C	Driftstemperatur, max	120 °C
Temperaturområde Montage, min.	-25 °C	Temperaturområde Montage, max.	120 °C

Märkdata enligt IEC

testad enligt standard	IEC 60664-1, IEC 61984	Märkström, max. antal poler (Tu=20°C)	13 A
Märkström, max. antal poler (Tu=40°C)	13 A	Märkspänning vid överspänningsk./Nedsmutningsgrad II/2	500 V
Märkspänning vid överspänningsk./Nedsmutningsgrad III/2	320 V	Märkspänning vid överspänningskat./Nedsmutningsgrad III/3	250 V
Märkspänning vid överspänningsk./Nedsmutningsgrad II/2	4 kV	Märkspänning vid överspänningsk./Nedsmutningsgrad III/2	4 kV
Märkstötspänning vid överspänningsk./Nedsmutningsgrad III/3	4 kV		

Klassificeringar

ETIM 3.0	EC001284	ETIM 4.0	EC002643
ETIM 5.0	EC002643	ETIM 6.0	EC002643
eClass 6.2	27-26-11-01	eClass 7.1	27-44-04-01
eClass 8.1	27-44-04-01	eClass 9.0	27-44-04-01
eClass 9.1	27-44-04-01		

Anmärkningar

Anmärkningar	
IPC-konformitet	Konformitet: Produkterna utvecklas, tillverkas och levereras i enlighet med internationellt erkända standarder och normer, och uppfyller de egenskaper som garanteras i databladet resp. har designegenskaper i enlighet med IPC-A-610 "Klass 2". Övriga anspråk gällande produkterna kan bedömas på begäran.

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Tekniska data**Godkännanden**

Godkännanden



ROHS

Uppfyllelse

Downloads

Broschyr/Katalog

[FL ANALO.SIGN.CONV. EN](#)
[MB DEVICE MANUF. EN](#)
[CAT 2 PORTFOLIOGUIDE EN](#)
[FL MACHINE SAFETY EN](#)
[FL 72H SAMPLE SER EN](#)
[PO OMNIMATE EN](#)

Teknikuppgifter

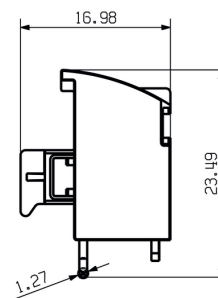
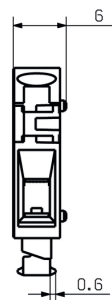
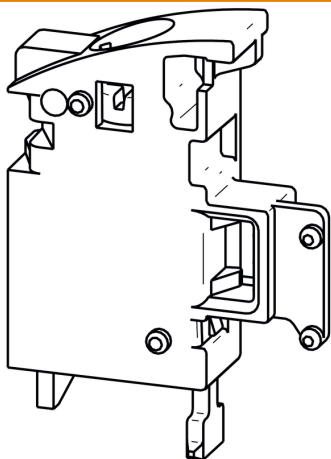
[EPLAN, WSCAD](#)

Teknikuppgifter Data

[STEP](#)

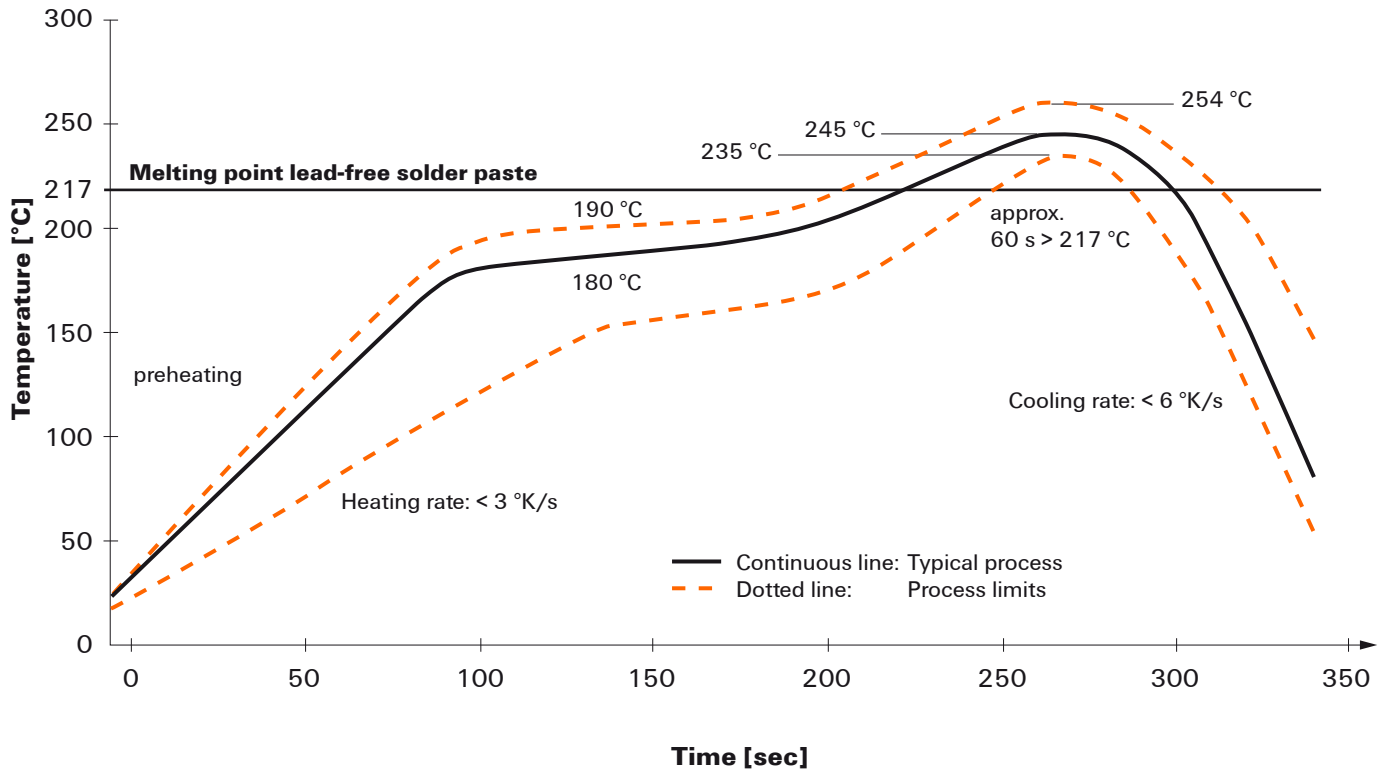
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Ritningar

Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.

Recommended wave soldering profiles

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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Recommended wave soldering profiles

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